VIGON® A 200+

Water-based defluxing agent for low pressure cleaning processes

VIGON® A 200+ was specifically developed for low and medium pressure spray-in-air processes with long exposure times. VIGON® A 200+ is a MPC® based cleaning agent recommended for removing a wide range of flux residues from electronic assemblies. VIGON® A 200+ ´s mild formula is particularly gentle on all solder joints and materials.

Areas of application: PCB cleaning		**Further information for this product:**
Low solid flux residues	++	**Technical Information Sheet 2**: Removability overview list
Rosin based flux residues	++	**Technical Information Sheet 3**: Material compatibility overview
Water soluble flux residues	++	**Application Recommendation**: Initial process parameters recommendation
Solder paste (unsoldered)	+	**MPC® Technology Sheet:** Detailed information on the MPC® Technology
SMT or conductive adhesives	o	

++ highly recommended, best results + recommended o possible

Cleaning trials in ZESTRON´s Technical Centers

Free of charge cleaning trials can be performed at one of ZESTRON's global Application Technology Centers. ZESTRON's American, European and Asian Technology Centers feature spray-in-air, ultrasonic and spray-under-immersion processes. This provides for an extensive overview on all available processes by leading equipment manufacturers and offers the user a unique testing opportunity. Please consult with ZESTRON's Application Technology Centers on future cleaning trials.

Advantages over other cleaners:

- Specifically developed for batch cleaning applications.
- Ability to remove a wide range of flux residues.
- Excellent material compatibility even with long contact times.
- High bath loading capacity ensures extended bath life, low maintenance costs and reduced costs per cleaned part.
- Surfactant-free formulation eliminates the formation of white residues on cleaned parts and cleaning equipment and eliminates time-consuming surfactant monitoring.
- Mild formulation results in shiny solder points and low ionic contamination.
- Does not foam, even in high pressure applications.

Please check material compatibility and refer to the material compatibility list, before cleaning plastics.

Process	Cleaning	Rinsing	Drying
Spray-in-air	VIGON® A 200+	DI-water	Hot air or circulating air
Centrifugal Cleaning	VIGON® A 200+	DI-water	Hot air or circulating air

Technical Data Please note that the information above represents VIGON® A 200+ at a 15 % concentration.		
Density	(g/ccm) at 20°C/68°C	1
Surface tension	(mN/m) at 25°C/77°F	31.7
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-Value	10g/l H_2O	9.9
Vapor pressure	(mbar) bei 20°C/68°F	20
Cleaning temperature	°C/°F	40 – 60 / 104 - 140
Solubility in water		Soluble
Application concentration	%	15 - 20
HMIS Rating	Health, Flammability, Reactivity	1 – 0 – 0

Lead-free Compliant:

VIGON® A 200+ meets the new RoHS & WEEE guidelines as well as current worker safety standards and the actual applicable environmental requirements. Its formulation is free of any other banned hazardous substances.

Extensive lead-free defluxing with VIGON® A 200+ was successfully completed by our Application Technology Centers. For further details please check our Technical Information Sheet 2.

Environmental, health and safety regulations:

VIGON® A 200+ is water-based and biodegradable. The cleaning agent does not contain any halogenated compounds and is not considered a hazardous material. No special precaution is required in the handling of the VIGON® A 200+.

Availability/Storage:

VIGON® A 200+ is available as concentrate in 1L bottles, 5L and 25L plastic canisters or 200L drums. Store VIGON® A 200+ in the original container in a temperature between 41- 86°F / 5 - 30°C. The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning Standards:

Cleaning with VIGON® A 200+ was successfully tested and passed the strengthens electronic manufacturing industry standards:

- Visual cleanliness in accordance with IPC-610A
- Ionic cleanliness in accordance with J-STD 001D
- Surface tension in accordance with IPC-TM 650 and DIN 32513
- Solderability according to J-STD 003

Alternative product recommendation:

For water-based defluxing of electronic assemblies in high pressure spray-in-air processes we also recommend VIGON® A 201.

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